

**Monday 5
October**

	9:30		12:30	14:00		15:40	16:00		18:00
		11th European FIB Users Group Meeting, EFUG workshop				Tutorial "Thermal Management of power electronics systems"	Coffee break	Workshop "Reliability on harsh environment"	
		11th European FIB Users Group Meeting, EFUG workshop							

**Tuesday 6
October**

	8:50		10:30	10:50		12:30	14:00	14:20	15:00	15:40	16:00		17:40	18:00			
		Tutorial "MEMS Reliability: Where are we now?"		Coffee break		Tutorial "ESD testing of devices, ICs and systems"		Lunch		Conf. Opening	Invited "Process dependence of BTI reliability in advanced HK MG stack"	Best Paper IRPS	Best Paper IPFA	Coffee break	Session A : Quality and Reliability Techniques for Devices and Systems	Presentation of Exhibitors	Author's corner

**Wednesday 7
October**

	8:30		10:30	10:50		12:30	12:50	14:00		15:40	16:00		16:40		18:00	19:30
		Session F : Extreme environments: Power devices reliability Invited "Reliability challenges of automotive power electronics"		Coffee break		Session F : Extreme environments: Power devices, automotive and spatial electronics reliability	Author's corner		Lunch		Session E : Packaging, Passive Components and MEMS Invited "Quasi hermetic packaging for new generation of spaceborn microwave equipment"	Author's corner	Coffee break			Workshop EUFANET

**Thursday 8
October**

	8:30		10:30	10:50	11:10		12:50	13:10	14:20		16:20	16:40		18:00
		Session B2: Failure Mechanisms in Si technologies and Nanoelectronics (Low K materials, Cu interconnects, ESD ...) Invited "Do ESD fails in systems correlate with IC ESD robustness?"	Author's corner	Coffee break		Session E : Packaging, Passive Components and MEMS Invited "Reliability, Prognostics and Risk Assessment Modelling for Electronics Packaging"	Author's corner	Lunch		Session B1: Failure Mechanisms in Si technologies and Nanoelectronics : NBTI Invited : Best Paper RCJ	Coffee break		Session B1: Failure Mechanisms in Si technologies and Nanoelectronics : Oxide Reliability	Author's corner

**Friday 9
October**

	8:30		10:10	10:30	10:50		12:30	13:00
		Session D: Failure Mechanisms in Microwave and High Bandgap Devices Invited "GaN HEMT Reliability"	Author's corner	Coffee break		Session D: Failure Mechanisms in Photonic Devices Invited "Towards Reliable Thin-Film Encapsulation of Organic Electronic Devices"		BPA And closing
		LOTUS Workshop				LOTUS Workshop		